

BB02-YP :- 1.0mm X 1.0mm ( 0.039" X 0.039" ) SMD PIN HEADER, DUAL ROW, R/A - 04 TO 30 CONTACTS

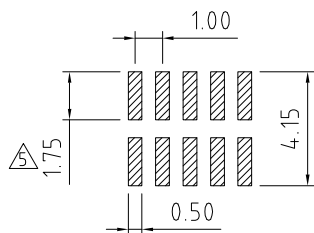
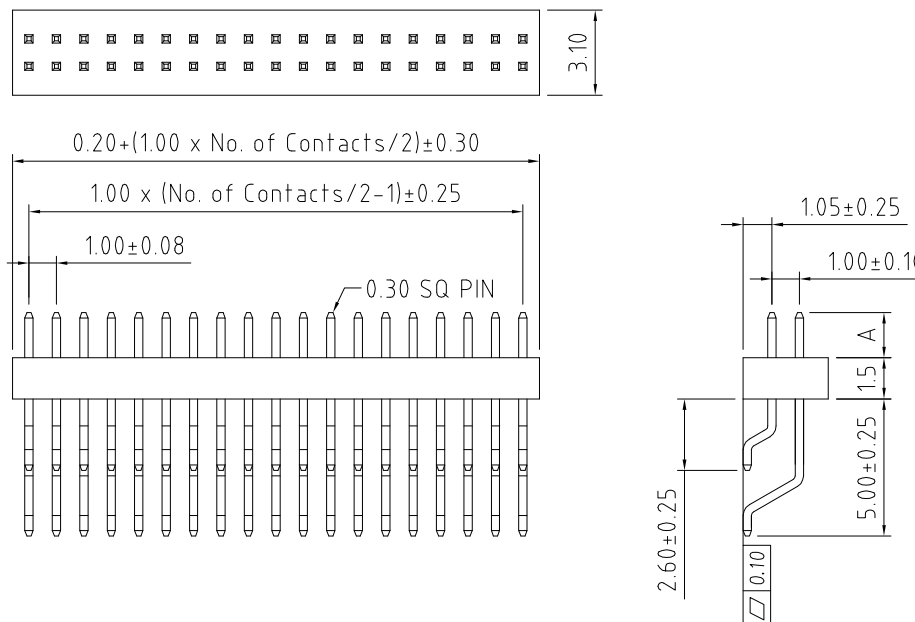
SPECIFICATIONS

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
CONTACTS RESISTANCE	20 m OHMS MAX.
DIELECTRIC WITHSTANDING	AC 300V
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD: LCP
PLATING	GOLD, TIN, OR SELECTIVE OVER MIN. 30U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC MANUAL SOLDER: 380°C FOR 3-5 SEC

NOTES:

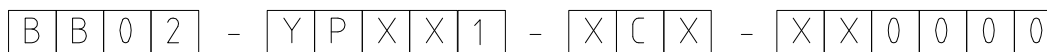
1. THE PACKAGING FOR 04 TO 08 CONTACTS IS BOX INSTEAD OF TUBE.

MATES WITH :- BB02-WA



RECOMMENDED PC BOARD SMD LAYOUT  
(TOLERANCE: ±0.05)

HOW TO ORDER



NO. OF CONTACTS:  
04 TO 30

CONTACT PLATING OPTIONS:  
K = GOLD FLASH (STANDARD)  
T = BRIGHT TIN  
M = MATT TIN

INSULATOR  
THICKNESS=1.5MM

PACKAGING OPTIONS:  
3 - TUBE (SEE NOTE.1)  
6 - T & R  
7 - T & R + FILM

PIN LENGTH 'A' (1/10mm)  
PLEASE SPECIFY PIN  
LENGTH REQUIRED IN mm  
I.E. 2.5mm = 25  
STANDARD = 1.5  
TOL. ±0.25mm

REV.	DATE & DRN	DESCRIPTION
10	03/07/09	CHC RELEASE
11	14/07/09	NYM SPECIFICATION
12	03/08/10	NYM 2
13	03/08/10	NYM 3
14	03/08/10	AMEND PIN NUMBERS
15	27/09/11	NYM
16	27/09/11	AMEND PLATING OPTIONS
17	13/03/12	NYM
18	13/03/12	REMOVE INSULATOR THICKNESS OPTION C
19	14/07/13	NYM
20	14/07/13	AMEND PCB LAYOUT

Scale: 5:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 XXX ± 0.10	Material SEE NOTE	 www.gradconn.com	Type: BB02-YP
Drawn: CHC			NOT TO SCALE		BB02-YP
App'd: XXX	Title: PIN HEADER				Drawing Number:
Date: 11 JAN. '13	Revision: 15		UNIT: mm		Sheet 1 of 1
					Drawing © E and O E